

California Eastern Laboratories

January 15, 2010

To: All CEL customers using NEC parts

Subject: Product Change Notification
PCN: OS/FO/RF_P20100112A

Dear CEL Customers:

The forthcoming expected merger of NEC Electronics Corporation and Renesas Technology Corporation into the new company Renesas Electronics Corporation requires logo and marking changes on certain NEC parts and packaging materials.

The effective date of the merger is April 1, 2010. From that date forward, newly marked products and packaging materials will begin to ship while current inventories are depleted. Products in inventory and distribution may be mixed between the old and new styles of marking and labeling.

This change affects all NEC Electronics devices that are sold by California Eastern Laboratories. This includes all RF semiconductors, fiber optic devices, optocouplers, and solid state relays.

The changes include all NEC markings on products, labels, and packaging. Please see attached NEC notification MAA-A-09-0154 for details.

Devices that currently have the NEC logo will no longer have a company logo marked on them. Those devices that are too small and have never had an NEC logo will not have a change to the current marking. Please see examples in the attached.

This will not result in any changes to the products themselves and does not affect product performance or characteristics.

We appreciate your understanding and acceptance related to these changes. An official Part Change Notification (PCN) form is also enclosed. Should you have questions or concerns, please contact your local CEL Field Sales Office.

Sincerely,



James A. West
Director, Quality
California Eastern Laboratories

CEL Product Change Notice

PCN OS/FO/RF_P20100112A

Customer: To all of our customers

NEC Product Type: All semiconductor products (including development tools) (excluding customer dedicated marking products)

Change Description: Marking change from the format of NEC Electronics Corp to the format of new company. (affects both product and packaging materials).

Reason for Change: NEC Electronics will merge with Renesas Technology Corporation on April 1, 2010 and a new company Renesas Electronics Corp will be established.

Schedule of Change: April 1, 2010 (Products with the above implementation will be introduced as current inventories are depleted).

Data Attached: Example of marking format change
Example of label and packing material change

Should you have a need for further details or have any questions, please contact your local CEL Field Sales Office.

Initiator	Title	Date	Contact Information
Jim West	Director, Quality	January 15, 2010	PCN@CEL.com

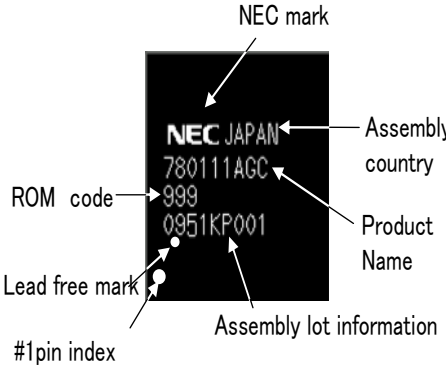
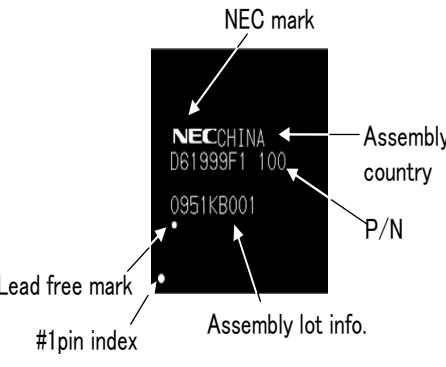
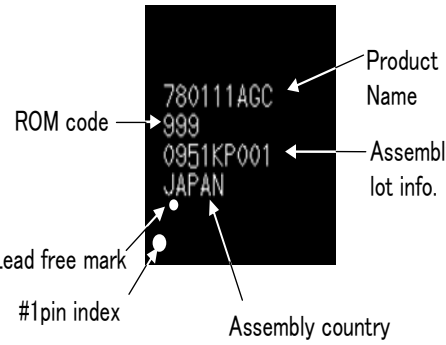
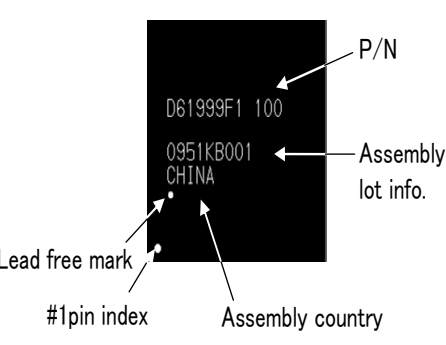
Attached Materials (1/11)

MAA-A-09-0154

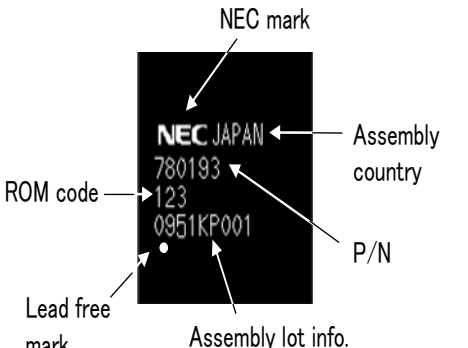
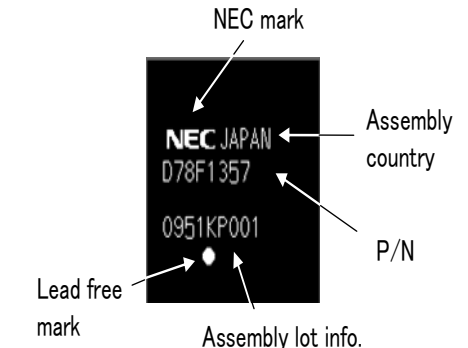
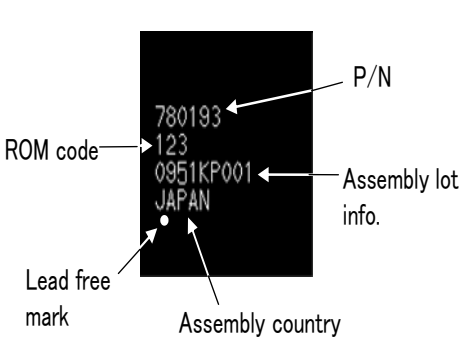
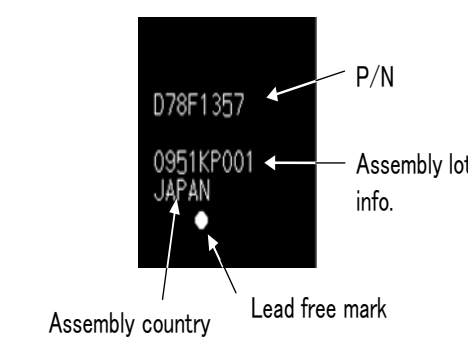
Examples: The Change of Marking, Label and Packing

Item	Contents of the Change		Example (Attached Page)
	Current	New	
Marking on device PKG	NEC mark	No mark	Package marking (1)~(5) (2~6/11)
Tray (with NEC mark)	NEC mark	Renesas mark	Tray, Magazine stick and Bag (7/11)
Magazine stick	NEC mark	Renesas mark	the same as above
Bag (with NEC mark)	NEC mark	Renesas mark	the same as above
Box	NEC mark ELECTRON DEVICE	Renesas mark No "ELECTRON DEVICE"	Box and Sealing tape (8/11)
Sealing tape	NEC mark	No mark	the same as above
Product label	NEC mark	Renesas mark	Product label (9/11)
Outer box label	Company name	New company name	Outer box label (10/11)
Protos carrier	NEC mark	No mark	Protos carrier (11/11)
Withdrawal indicator (with NEC)	NEC mark Company name	No mark No company name	the same as above

Example of Package Marking (1)

BGA PKG		
Current	 <p>Diagram illustrating the current marking for a BGA package assembled in Japan. The marking includes: NEC mark, NEC JAPAN (Assembly country), ROM code 780111AGC, 999 (Lead free mark), 0951KP001 (Product Name and Assembly lot information), and #1pin index.</p>	 <p>Diagram illustrating the current marking for a BGA package assembled in China. The marking includes: NEC mark, NEC CHINA (Assembly country), ROM code D61999F1 100 (P/N), 0951KB001 (Assembly lot info), and #1pin index.</p>
New	 <p>Diagram illustrating the new marking for a BGA package assembled in Japan. The marking includes: ROM code 780111AGC (Product Name), 999 (Lead free mark), 0951KP001 (Assembly lot info), and JAPAN (Assembly country). #1pin index is also present.</p>	 <p>Diagram illustrating the new marking for a BGA package assembled in China. The marking includes: ROM code D61999F1 100 (P/N), 0951KB001 (Assembly lot info), and CHINA (Assembly country). #1pin index is also present.</p>

Example of Package Marking (2)

QFP PKG		
Current	 <p>Diagram showing current package marking for a QFP package. The marking includes: NEC mark (top), NEC JAPAN (Assembly country), ROM code (780193, 123), P/N (0951KP001), Lead free mark (dot), and Assembly lot info. (0951KP001).</p>	 <p>Diagram showing current package marking for a QFP package. The marking includes: NEC mark (top), NEC JAPAN (Assembly country), P/N (D78F1357), Lead free mark (dot), and Assembly lot info. (0951KP001).</p>
New	 <p>Diagram showing new package marking for a QFP package. The marking includes: ROM code (780193, 123), P/N (0951KP001), Lead free mark (dot), Assembly country (JAPAN), and Assembly lot info. (0951KP001).</p>	 <p>Diagram showing new package marking for a QFP package. The marking includes: P/N (D78F1357), Assembly lot info. (0951KP001), Assembly country (JAPAN), and Lead free mark (dot).</p>

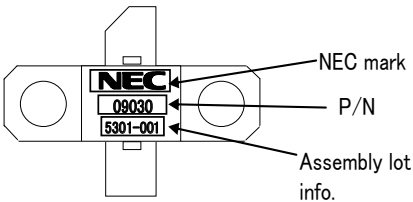
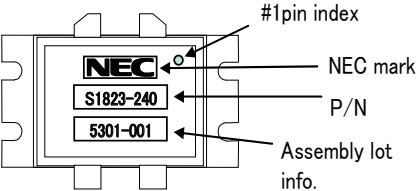
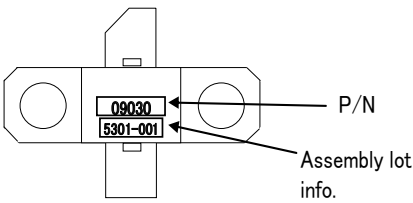
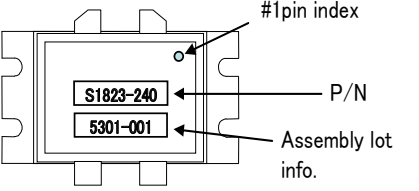
Example of Package Marking (3)

Other PKG	DIP PKG	SOP PKG
<p>Current</p>		
<p>New</p>		

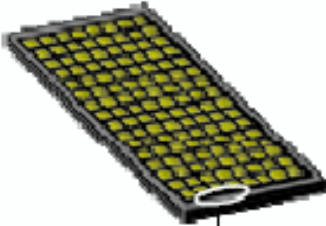
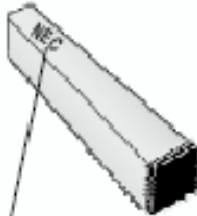

Example of Package Marking (4)

Power Device	TO-263 (MP-25ZK)	TO-220 (MP-25)	TO-126 (MP-5)
Current	<p>Diagram showing the current marking scheme for a TO-263 package. The marking includes the NEC logo, a lead-free mark (a dot), the part number (P/N), and the assembly lot information.</p>	<p>Diagram showing the current marking scheme for a TO-220 package. The marking includes the NEC logo, a lead-free mark (a dot), the part number (P/N), and the assembly lot information.</p>	<p>Diagram showing the current marking scheme for a TO-126 package. The marking includes the NEC logo, a lead-free mark (a dot), the part number (P/N), and the assembly lot information.</p>
New	<p>Diagram showing the new marking scheme for a TO-263 package. The marking includes a lead-free mark (a dot), the part number (P/N), and the assembly lot information. The NEC logo is no longer present.</p>	<p>Diagram showing the new marking scheme for a TO-220 package. The marking includes a lead-free mark (a dot), the part number (P/N), and the assembly lot information. The NEC logo is no longer present.</p>	<p>Diagram showing the new marking scheme for a TO-126 package. The marking includes a lead-free mark (a dot), the part number (P/N), and the assembly lot information. The NEC logo is no longer present.</p>

Example of Package Marking (5)

Compound Device (RF module)	FE-806 (T-91MPKG)	FE-446BM(T-92MPKG)
Current	 <p>Diagram of FE-806 package marking (Current). The marking includes the NEC logo, P/N 09030, and Assembly lot info 5301-001. Labels point to the NEC mark, P/N, and Assembly lot info.</p>	 <p>Diagram of FE-446BM package marking (Current). The marking includes the #1 pin index, NEC logo, P/N S1823-240, and Assembly lot info 5301-001. Labels point to the #1 pin index, NEC mark, P/N, and Assembly lot info.</p>
New	 <p>Diagram of FE-806 package marking (New). The marking includes P/N 09030 and Assembly lot info 5301-001. Labels point to the P/N and Assembly lot info.</p>	 <p>Diagram of FE-446BM package marking (New). The marking includes the #1 pin index, P/N S1823-240, and Assembly lot info 5301-001. Labels point to the #1 pin index, P/N, and Assembly lot info.</p>

Examples of Tray, Magazine Stick and Bag

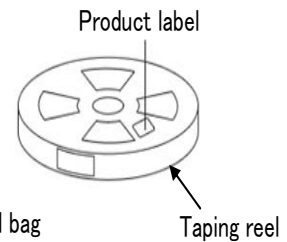
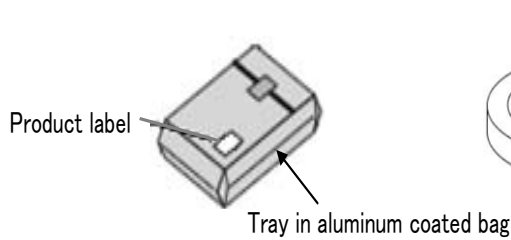
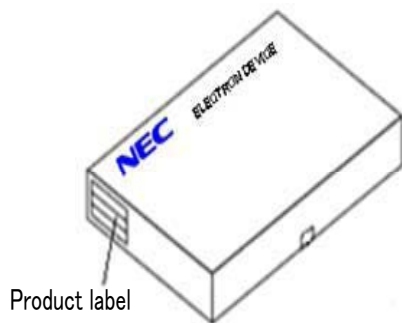
	Tray	Magazine Stick	Bag
Current	 <p>NEC mark</p>	 <p>NEC mark</p>	 <p>NEC mark</p>
New	Change to RENESAS mark from NEC mark		

Examples of Box and Sealing Tape

	Box	Sealing Tape
Current	<p>NEC mark</p> <p>ELECTRON DEVICE</p>	<p>Sealing tape with NEC mark</p>
New	<p>RENESAS mark</p> <p>Delete ELECTRON DEVICE</p>	<p>Sealing tape without NEC mark</p>

Examples of Product label

	Product label
Current	
New	



Example of Outer Box Label

Current	New
 <p>The current label features the following text: NEC ELECTRONICS CORPORATION (circled in red), Mark: NEC ELECTRONICS HONGKONG HKG (circled in red), Case No: FA63294E, GW: 3.9Kg NW: 3.4Kg CU: 0.024M3, BOX-ID: FA0000063294 (with barcode), P/O-1: HAS-741101 - 000001, P/O-2:, P/N Customer: UPD789104AC-P27-A, P/N Shipper: UPD789104AC-P27-A, Class: E Qty: 343, Origin: Assembled in JAPAN From wafers of CHINA L-146, NECロジスティクス 福岡航空貨物センター, OS-NO: UM436 343, and 出荷伝票番号: 0102482809/000010.</p>	 <p>The new label features the following text: Renesas Electronics Corporation (circled in red), Mark: New company name (circled in red), Case No:, GW: 3.9Kg NW: 3.4Kg CU: 0.024M3, BOX-ID: FA0000063294 (with barcode), P/O-1: HAS-741101 - 000001, P/O-2:, P/N Customer: UPD789104AC-P27-A, P/N Shipper: UPD789104AC-P27-A, Class: E Qty: 343, Origin: Assembled in JAPAN From wafers of CHINA L-146, NECロジスティクス 福岡航空貨物センター, OS-NO: UM436 343, and 出荷伝票番号: 0102482809/000010.</p>

Example of Protos Carrier (Wafer Carrying Case)

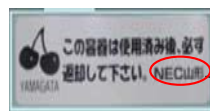
- NEC mark molded on the case will be deleted
- NEC mark or NEC company name in a withdrawal indicator label on the case will be deleted

Protos carrier



NEC mark will be deleted

Withdrawal indicator



NEC company name will be deleted